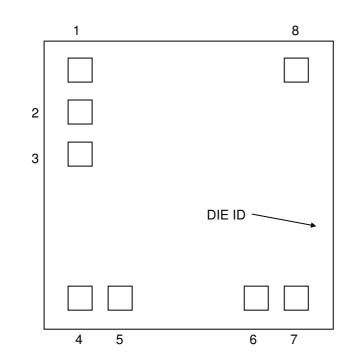


PAD LAYOUT



PAD	FUNCTION		
1	INPUT FREQ COMP A		
2	- INPUT		
3	+ INPUT		
4	V-		
5	OUTPUT FREQ COMP		
6	OUTPUT		
7	V+		
8	INPUT FREQ COMP B		

NOTE

- This data is supplied for general information only and is believed to be correct at the time of publication.
- For critical applications, the customer is advised to verify device revision and pad coordinates, prior to processing
- Changes can be made without notification from the manufacturer. Diedevices cannot accept liability in that event

DEVICE	UA709	DIE SIZE (MILS)	38 X 38 X 14
MANUFACTURER	FAIRCHILD	BOND PADS (MILS)	4 X 4
APPROVED BY	GEW	TOP METAL	Al
DATE	05/05/22	BACK METAL	Si
SERIAL NUMBER	1170	BACK POTENTIAL	V-

